

2018 20th International Conference on Electronic Materials and Packaging (EMAP 2018)

**Clear Water Bay, Hong Kong
17 – 20 December 2018**



IEEE Catalog Number: CFP18506-POD
ISBN: 978-1-5386-5643-3

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|-------------------------|-------------------|
| IEEE Catalog Number: | CFP18506-POD |
| ISBN (Print-On-Demand): | 978-1-5386-5643-3 |
| ISBN (Online): | 978-1-5386-5642-6 |

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